



Specification of Automotive MLCC (Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B333KB8WPNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 33nF, 50V, ±10%, X7R, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>333</u> <u>K</u> <u>B</u> <u>8</u> <u>W</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	0603 (inch code)	L: 1.6	3 ± 0.1 mm	W:	0.8 ± 0.1 mm	
3	Dielectric	X7R	8	Inner electrode		Ni , Open mode	
4	Capacitance	33 nF		Termination		Soft Termination	
⑤	Capacitance	±10 %		Plating		Sn 100% (Pb	Free)
	tolerance		9	Product		Automotive	
6	Rated Voltage	50 V	100	Grade code		Standard	
7	Thickness	0.8 ± 0.1 mm	11	Packaging		Cardboard Type, 7" r	reel

B. Reliability Test and Judgement condition

	Performance	Test condition		
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150 ℃		
Exposure	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion		
	Tan δ: 0.03 max			
	IR : More than 10,000⋒Ω or 500⋒Ω× <i>μ</i> F			
	Whichever is Smaller			
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles		
	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion		
	Tan δ : 0.03 max	1 cycle condition :		
	IR : More than 10,000⋒Ω or 500⋒Ω×μF	-55+0/-3℃(15±3min) -> Room Temp(1min.)		
	Whichever is Smaller	-> 125+3/-0°C (15±3min) -> Room Temp(1min.)		
Destructive Physical No Defects or abnormalities		Per EIA 469		
Analysis				
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle		
	Capacitance Change : Within ±12.5%	Heat (25~65 ℃) and humidity (80~98%), Unpowered		
	Tan δ : 0.03 max	measurement at 24±2hrs after test conclusion		
	IR : More than 10,000⋒Ω or 500⋒Ω×μF			
	Whichever is Smaller			
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85℃/85%RH, Rated Voltate and 1.3~1.5V,		
	Capacitance Change : Within ±12.5%	Add 100kohm resistor		
	Tan δ : 0.035 max	Measurement at 24±2hrs after test conclusion		
	IR : More than 500MΩ or 25MΩ×μF	The charge/discharge current is less than 50mA.		
	Whichever is Smaller			
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125 ℃, 200% Rated Voltage,		
Operating Life	Capacitance Change : Within ±12.5%	Measurement at 24±2hrs after test conclusion		
	Tan δ : 0.035 max	The charge/discharge current is less than 50mA.		
	IR : More than 1000MΩ or 50MΩ×μF			
	Whichever is Smaller			

	Performance	Test condition				
External Visual	No abnormal exterior appearance	Microscope ('10)				
Physical Dimensions Within the specified dimensions		Using The calipers				
Mechanical Shock	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) Peakvalue Duration Wave Velocity 1,500G 0.5ms Half sine 4.7m/sec.				
Vibration	Appearance : No abnormal exterior appearance Capacitance Change : Within $\pm 10\%$ Tan δ , IR : initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"×5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000Hz.				
Resistance to Solder Heat	Appearance : No abnormal exterior appearance Capacitance Change : Within $\pm 10\%$ Tan δ , IR : initial spec.	Solder pot : 260±5℃, 10±1sec.				
Thermal Shock	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	-55℃/+125℃. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air				
ESD	Appearance : No abnormal exterior appearance Capacitance Change : Within $\pm 10\%$ Tan δ , IR : initial spec.	AEC-Q200-002				
Solderability	95% of the terminations is to be soldered evenly and continuously	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5°C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5°C solder: a solution ethanol and rosin				
Electrical Characterization	Capacitance : Within specified tolerance Tan δ (DF): 0.025 max. IR(25 ℃): More than 10,000 MΩ or 500 MΩ×μF IR(125 ℃): More than1,000 MΩ or 10 MΩ×μF Whichever is Smaller Dielectric Strength	The Capacitance /D.F. should be measured at 25°C, 1⊮z±10%, 1.0±0.2Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25°C, @125°C for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds				
Board Flex	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10%	Bending to the limit (2mm) for 5 seconds				
Terminal Strength(SMD)	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10%	10N, for 60±1 sec.				
Beam Load	Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N	Beam speed 0.5±0.05mm/sec				
Temperature Characteristics	X7R (From -55℃ to 125℃, Capacitance change shou	ıld be within ±15%)				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.